

# SOT195

plastic single-ended flat package; 4 in-line leads

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	S (single)
<b>Package type descriptive code</b>	SIP4
<b>Package type industry code</b>	SIP4
<b>Package style descriptive code</b>	SIP (single in-line package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	T (through-hole mount)
<b>Issue date</b>	2-6-1997

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5	-	5.1	5.2	mm
E	package width	4.4	-	4.6	4.8	mm
A <sub>2</sub>	package height	1.6	-	1.7	1.8	mm
n <sub>2</sub>	actual quantity of termination	-	-	4	-	



## 2. Package outline

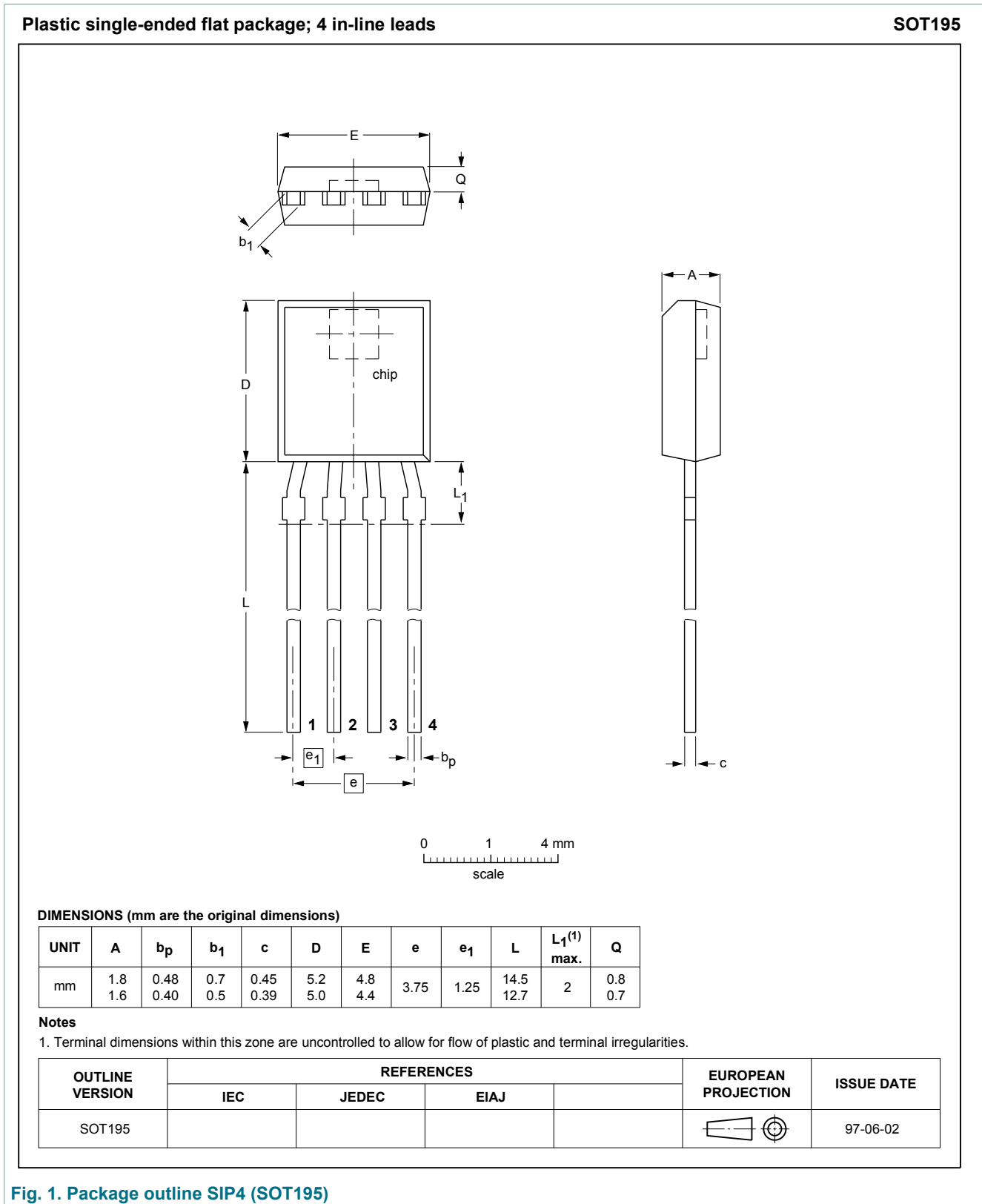


Fig. 1. Package outline SIP4 (SOT195)

### 3. Legal information

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